

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A polishing body, ~~having~~ comprising:
a polishing part with a predetermined shape molded from a residue or a dried powder;
said residue or dried powder being prepared by eliminating a dispersion medium from
an aqueous dispersion ~~wherein comprising~~ a matrix material and abrasive ~~are dispersed and~~
~~contained respectively.~~

Claim 2 (Currently Amended): The polishing body according to Claim 1, wherein a
method for eliminating of said dispersion medium is a spray drying method.

Claim 3 (Original): The polishing body according to Claim 1, wherein the polishing
body is used for the polishing of semiconductors.

Claim 4 (Currently Amended): A polishing body, ~~having~~ comprising:
a polishing part with a predetermined shape molded from a residue or a dried powder;
said residue or dried powder being prepared by eliminating a dispersion medium from
an aqueous dispersion ~~containing~~ comprising dispersed composite particles ~~wherein~~
comprising an abrasive is attached to a matrix material.

Claim 5 (Currently Amended): The polishing body according to Claim 4, wherein a
method for eliminating of said dispersion medium is a spray drying method.

Claim 6 (Currently Amended): The polishing body according to Claim 4, wherein
said aqueous dispersion further comprises a matrix material and/or an abrasive ~~are dispersed~~
~~and contained in said aqueous dispersion.~~

Claim 7 (Original): The polishing body according to Claim 4, wherein the respective
zeta potentials of said matrix material and said abrasive are opposite in sign and the
difference of said zeta potentials is 5mV or more.

Claim 8 (Original): The polishing body according to Claim 4, wherein the polishing
body is used for the polishing of semiconductors.

Claim 9 (Currently Amended): A polishing body, having comprising:
a polishing part with a predetermined shape molded from a residue or a dried powder;
said residue or dried powder being prepared by eliminating a dispersion medium from
an aqueous dispersion ~~wherein~~ containing 1) a matrix material ~~comprised of~~ comprising a
crosslinkable polymer and 2) an abrasive ~~are dispersed and contained respectively, which~~
said crosslinkable polymer being is crosslinked during drying eliminating of said
dispersion medium, or during molding, or after molding, ~~and which has thereby obtaining a~~
crosslinked structure.

Claim 10 (Currently Amended): The polishing body according to Claim 9, wherein a
method for eliminating of said dispersion medium is a spray drying method.

Claim 11 (Original): The polishing body according to Claim 9, wherein the polishing
body is used for the polishing of semiconductors.

Claim 12 (Currently Amended): A polishing body, having comprising:
a polishing part with a predetermined shape molded from a residue or a dried powder;
said residue or dried powder being prepared by eliminating a dispersion medium from
an aqueous dispersion containing dispersed composite particles wherein comprising an
abrasive is attached to a matrix material, said matrix material comprising comprised of a
crosslinkable polymer, which
said crosslinkable polymer being is crosslinked during drying eliminating of said
dispersion medium, or during molding, or after molding, and which has thereby obtaining a
crosslinked structure.

Claim 13 (Currently Amended): The polishing body according to Claim 12, wherein
a method for eliminating of said dispersion medium is a spray drying method.

Claim 14 (Original): The polishing body according to Claim 12, wherein the
respective zeta potentials of said matrix material and said abrasive are opposite in sign and
the difference of said zeta potentials is 5mV or more.

Claim 15 (Original): The polishing body according to Claim 12, wherein the
polishing body is used for the polishing of semiconductors.

Claim 16 (New): A method for producing a polishing body, comprising:
eliminating a dispersion medium from an aqueous dispersion which comprises a
matrix material and abrasive, thereby obtaining a residue or a dried powder; and

molding said residue or said dried powder to produce a polishing part with a predetermined shape.

Claim 17 (New): A method for producing a polishing body, comprising:
eliminating a dispersion medium from an aqueous dispersion containing dispersed composite particles which comprise an abrasive attached to a matrix material, thereby obtaining a residue or a dried powder; and

molding said residue or said dried powder to produce a polishing part with a predetermined shape.

Claim 18 (New): A method for producing a polishing body, comprising:
eliminating a dispersion medium from an aqueous dispersion which comprises 1) a matrix material, said matrix material comprising a crosslinkable polymer and 2) an abrasive, thereby obtaining a residue or a dried powder;

molding said residue or said dried powder to produce a polishing part with a predetermined shape; and

forming a crosslinked structure during the elimination of the dispersion medium, during molding the polishing part, or after molding the polishing part.

Claim 19 (New): A method for producing a polishing body, comprising:
eliminating a dispersion medium from an aqueous dispersion containing dispersed composite particles which comprise an abrasive attached to a matrix material, thereby obtaining a residue or a dried powder;

molding said residue or said dried powder to produce a polishing part with a predetermined shape; and

forming a crosslinked structure during the elimination of the dispersion medium,
during molding the polishing part, or after molding the polishing part.

Claim 20 (New): A polishing pad, which comprises the polishing body according to
Claim 1.

Claim 21 (New): A polishing pad, which comprises the polishing body according to
Claim 4.

Claim 22 (New): A polishing pad, which comprises the polishing body according to
Claim 9.

Claim 23 (New): A polishing pad, which comprises the polishing body according to
Claim 12.

Claim 24 (New): A method for polishing of semiconductors, comprising:
polishing a semiconductor with the polishing body according to Claim 1.

Claim 25 (New): A method for polishing of semiconductors, comprising:
polishing a semiconductor with the polishing body according to Claim 4.

Claim 26 (New): A method for polishing of semiconductors, comprising:
polishing a semiconductor with the polishing body according to Claim 9.

Claim 27 (New): A method for polishing of semiconductors, comprising:

polishing a semiconductor with the polishing body according to Claim 12.

BASIS FOR THE AMENDMENT

The Claims have been amended to better conform to accepted U.S. claim format.
New Claims 16-27 have been added as supported by the specification at pages 2-35.

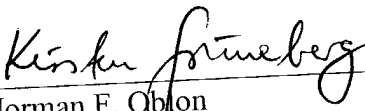
No new matter is believed to have been added by entry of this amendment. Entry and favorable reconsideration are respectfully requested.

Upon entry of this amendment Claims 1-27 will now be active in this application.

Applicants submit that the present application is now in condition for examination on the merits and early notice of such action is earnestly solicited.

Respectfully submitted,

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